



## Material Content Data Sheet



Halogen-Free

<b>Sales Product Name</b>	IPC100N04S5L-1R5	<b>Issued</b>	21. July 2021
<b>MA#</b>	MA005613584		
<b>Package</b>	PG-TDSON-8-34	<b>Weight*</b>	112.75 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.110	0.98	0.98	9848	9848
leadframe	inorganic material	phosphorus	7723-14-0	0.016	0.01		141	
	non noble metal	iron	7439-89-6	0.053	0.05		469	
	non noble metal	copper	7440-50-8	52.842	46.88	46.94	468674	469284
wire	noble metal	gold	7440-57-5	0.046	0.04	0.04	410	410
encapsulation	organic material	carbon black	1333-86-4	0.075	0.07		667	
	plastics	epoxy resin	-	5.942	5.27		52705	
	inorganic material	silicondioxide	60676-86-0	31.592	28.02	33.36	280205	333577
leadfinish	non noble metal	tin	7440-31-5	1.574	1.40	1.40	13959	13959
plating	noble metal	silver	7440-22-4	0.209	0.19	0.19	1856	1856
solder	non noble metal	tin	7440-31-5	0.030	0.03		264	
	noble metal	silver	7440-22-4	0.037	0.03		330	
	non noble metal	lead	7439-92-1	1.422	1.26	1.32	12612	13206
heat sink clip	inorganic material	phosphorus	7723-14-0	0.005			45	
	non noble metal	iron	7439-89-6	0.017	0.01		149	
	non noble metal	copper	7440-50-8	16.828	14.92	14.93	149250	149444
clip plating	noble metal	silver	7440-22-4	0.639	0.57	0.57	5667	5667
heatspreader	inorganic material	phosphorus	7723-14-0	0.000			1	
	non noble metal	iron	7439-89-6	0.000			3	
	non noble metal	copper	7440-50-8	0.310	0.27	0.27	2745	2749
*deviation	< 10%	Sum in total:				100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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